

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Application Serial No. 09/536,037
 Filing Date March 27, 2000
 Inventor Weimin (Michael) Li
 Assignee Micron Technology, Inc.
 Group Art Unit 2822
 Examiner T. Thomas
 Attorney's Docket No. MI22-1398
 Title: Low k Interlevel Dielectric Layer Fabrication Methods

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
 References -- See Attached Form PTO-1449

Box GROUP ART UNIT 2822
 Assistant Commissioner for Patents
 Washington, D.C. 20231

REMARKS

The Examiner's attention is directed to the reference which is listed on the attached Form PTO-1449 and copy of which is attached. No admission is made regarding whether all the submitted references are prior art.

Citation of this patent is respectfully requested.

This Information Disclosure Statement is being filed within three months of the filing date of the Request For Continued Examination (RCE) filed August 31, 2001. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this information disclosure statement, please charge the fee specified under 37 C.F.R. §1.17(p) to Deposit Account No. 23-0925. Please credit Deposit Account No. 23-0925 with any overpayment of the above fee.

Respectfully submitted,

Date: Nov 15, 2001

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